

IN THE CLAIMS:

Please cancel claim 39 without prejudice.

Please amend claims 37, 38, and 40-42 so that pending claims 37, 38, and 40-43 read as follows:

37. (Twice Amended) Method of fabricating tip structures for ends of contact structures, comprising:

depositing at least one layer of at least one conductive material on a surface of a substrate;

depositing a layer of masking material atop the at least one conductive layer;

patterning openings in the masking material;

depositing at least one layer of at least one conductive tip material into the openings, forming tip structures;

removing the masking material;

joining the tip structures to contact structures; and

releasing the tip structures from the substrate.

38. (Amended) Method, according to claim 37, further comprising:

depositing a joining material on the at least one layer of at least one conductive tip material previously deposited in the openings.

40. (Amended) Method, according to claim 37, wherein:

the contact structures are resilient contact structures.

41. (Amended) Method, according to claim 37, wherein:

the contact structures are composite interconnection elements.

42. (Amended) Method, according to claim 37, wherein:

the contact structures are resilient contact structures disposed atop a space transformer of a probe card assembly.

43. Method, according to claim 37, wherein said substrate is a sacrificial substrate.

Please add new claims 44-54 as follows:

44. (New) A method comprising:

fabricating a plurality of tip structures on a sacrificial substrate;
joining said tip structures to a plurality of contact structures; and
releasing said plurality of tip structures from said sacrificial substrate.

45. (New) The method of claim 44, wherein said step of fabricating a plurality of tip materials comprises depositing tip material in a plurality of openings in a masking material formed on said sacrificial substrate.

46. (New) The method of claim 44, wherein said step of fabricating a plurality of tip materials comprises:

depositing first material on said sacrificial substrate;
depositing a masking material on said first material;
patterning openings in said masking material; and
depositing tip material into said openings.

47. (New) The method of claim 46, wherein said first material comprises a plurality of layers.

48. (New) The method of claim 46, wherein said tip material comprises a plurality of layers.

49. (New) The method of claim 44 further comprising forming said contact structures on a substrate.

50. (New) The method of claim 49, wherein said step of forming said contact structures on a substrate comprises bonding wires to said substrate.

51. (New) The method of claim 50, wherein said step of forming said contact structures on a substrate further comprises over coating said wires.

52. (New) The method of claim 49, wherein said step of forming said contact structures on a substrate comprises planarizing ends of said contact structures.

53. (New) The method of claim 52, wherein said step of joining said tip structures to a plurality of contact structures comprises joining said tip structures to said ends of said contact structures.

54. (New) The method of claim 44, wherein said contact structures are elongate, and said step of joining said tip structures to said contact structures comprises joining said tip structures to free ends of said contact structures.